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SUMMARY

The novel electroplating solution disclosed comprises $CuSO_4 . 5H_2O$, H_2SO_4, Cl ions, Polyethylenglycol, and hydroxyl amine sulfate and hydroxyl amine chloride and if necessary further additives. The function of these additives is to prevent voids or seams formed in the copper film, to reduce the containing concentration of oxygen and other impurities and to keep the resistance of the copper film.

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